RFD3055LE, RFD3055LESM, RFP3055LE

11A, 60V, 0.107 Ohm, Logic Level, N-Channel Power MOSFETs

These N-Channel enhancement-mode power MOSFETs are manufactured using the latest manufacturing process technology. This process, which uses feature sizes approaching those of LSI circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. These transistors can be operated directly from integrated circuits.

Formerly developmental type TA49158.

Ordering Information

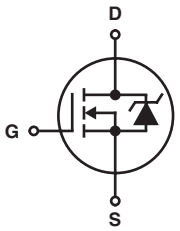
PART NUMBER	PACKAGE	BRAND
RFD3055LE	TO-251AA	F3055L
RFD3055LESM	TO-252AA	F3055L
RFP3055LE	TO-220AB	FP3055LE

NOTE: When ordering, use the entire part number. Add the suffix, 9A, to obtain the TO-252 variant in tape and reel, e.g. RFD3055LESM9A.

Features

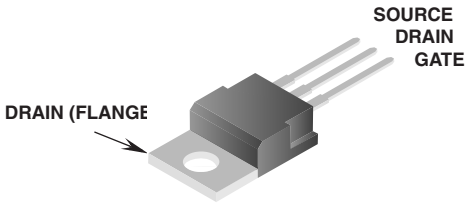
- 11A, 60V
- $r_{DS(ON)} = 0.107\Omega$
- Temperature Compensating PSPICE® Model
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- Related Literature
  - TB334 “Guidelines for Soldering Surface Mount Components to PC Boards”

Symbol

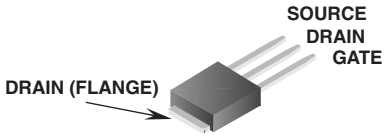


Packaging

JEDEC TO-220AB



JEDEC TO-251AA



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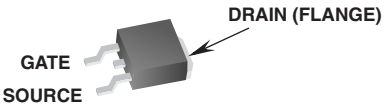

Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

		RFD3055LE, RFD3055LESM, RFP3055LE	UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	60	V
Drain to Gate Voltage (R_{GS} = 20kΩ) (Note 1)	V_{DGR}	60	V
Gate to Source Voltage	V_{GS}	±16	V
Continuous Drain Current	I_D	11	A
Pulsed Drain Current (Note 3)	I_{DM}	Refer to Peak Current Curve	
Single Pulse Avalanche Rating	E_{AS}	Refer to UIS Curve	
Power Dissipation	P_D	38	W
Derate Above 25^oC		0.25	$W/^oC$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175	^oC
Maximum Temperature for Soldering			
Leads at 0.063in (1.6mm) from Case for 10s	T_L	300	^oC
Package Body for 10s, See Techbrief 334	T_{pkg}	260	^oC

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^oC$ to 150^oC.

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	I_D = 250μA, V_{GS} = 0V		60	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, I_D = 250μA		1	-	3	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 55V, V_{GS} = 0V		-	-	1	μA
		V_{DS} = 50V, V_{GS} = 0V, $T_C = 150^oC$		-	-	250	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±16V		-	-	±100	nA
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	I_D = 8A, V_{GS} = 5V (Figure 11)		-	-	0.107	Ω
Turn-On Time	t_{ON}	$V_{DD} \approx$ 30V, I_D = 8A, V_{GS} = 4.5V, R_{GS} = 32Ω (Figures 10, 18, 19)		-	-	170	ns
Turn-On Delay Time	$t_{d(ON)}$			-	8	-	ns
Rise Time	t_r			-	105	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	22	-	ns
Fall Time	t_f			-	39	-	ns
Turn-Off Time	t_{OFF}			-	-	92	ns
Total Gate Charge	$Q_{g(TOT)}$	V_{GS} = 0V to 10V	V_{DD} = 30V, I_D = 8A, $I_{g(REF)}$ = 1.0mA (Figures 20, 21)	-	9.4	11.3	nC
Gate Charge at 5V	$Q_{g(5)}$	V_{GS} = 0V to 5V		-	5.2	6.2	nC
Threshold Gate Charge	$Q_{g(TH)}$	V_{GS} = 0V to 1V		-	0.36	0.43	nC
Input Capacitance	C_{ISS}	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz (Figure 14)		-	350	-	pF
Output Capacitance	C_{OSS}			-	105	-	pF
Reverse Transfer Capacitance	C_{RSS}			-	23	-	pF
Thermal Resistance Junction to Case	$R_{\theta JC}$			-	-	3.94	$^oC/W$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	TO-220AB		-	-	62	$^oC/W$
		TO-251AA, TO-252AA		-	-	100	$^oC/W$

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	I_{SD} = 8A		-	1.25	V
Diode Reverse Recovery Time	t_{rr}	I_{SD} = 8A, dI_{SD}/dt = 100A/μs		-	66	ns

NOTES:

2. Pulse Test: Pulse Width ≤ 300ms, Duty Cycle ≤ 2%.
3. Repetitive Rating: Pulse Width limited by max junction temperature. See Transient Thermal Impedance Curve (Figure 3) and Peak Current Capability Curve (Figure 5).

Typical Performance Curves Unless Otherwise Specified

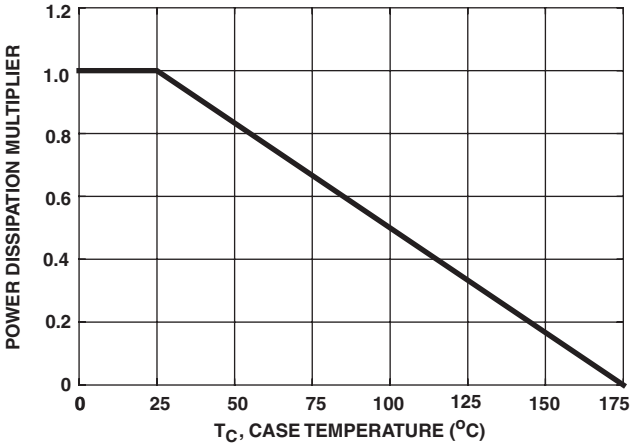

FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

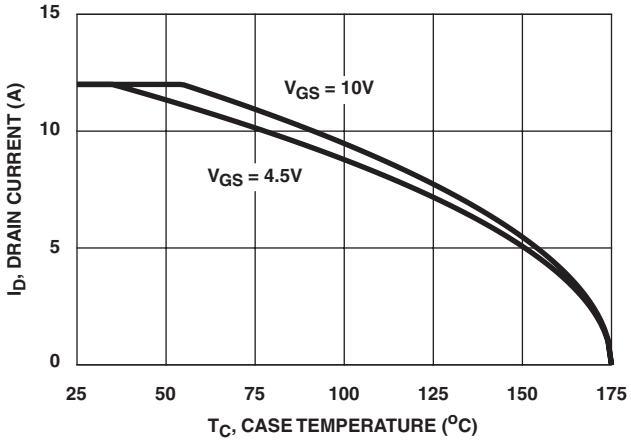

FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

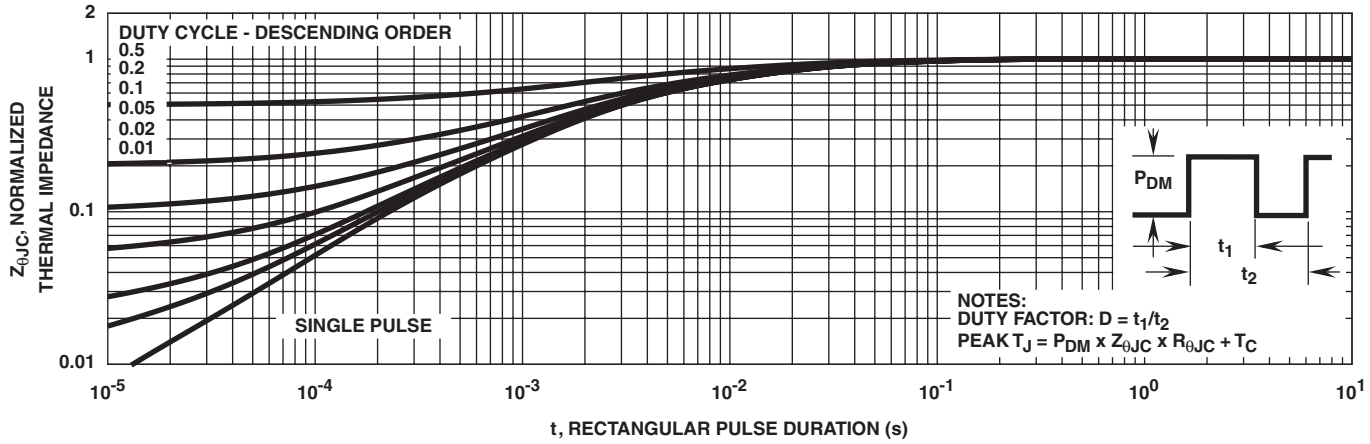

FIGURE 3. NORMALIZED TRANSIENT THERMAL IMPEDANCE

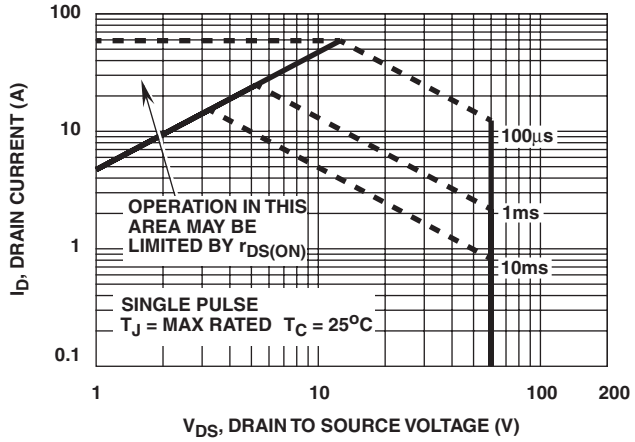

FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

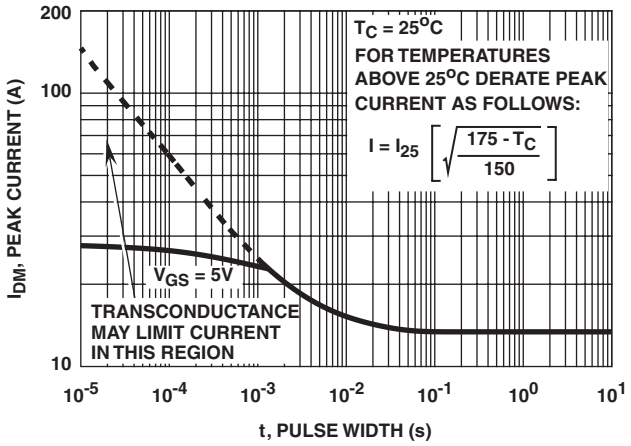

FIGURE 5. PEAK CURRENT CAPABILITY